imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







DUAL P-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- ESD Protected Gate to 1kV
- Low Input Capacitance
- Fast Switching Speed
- Lead Free By Design/RoHS Compliant (Note 2)
- "Green" Device (Note 3)
- Qualified to AEC-Q 101 Standards for High Reliability

Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)

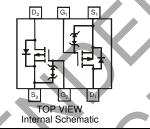
SOT-563





ESD protected to 1kV

TOP VIEW



Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

	Characteristic	Symbol	Value	Units
Drain-Source Voltage	Characteristic		-50	Units
0		VDSS		V
Gate-Source Voltage	Continuous	V _{GSS}	±8	V
Drain Current (Note 2)	Continuous	ID	-160	mA

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 1)	PD	400	mW
Thermal Resistance, Junction to Ambient (Note 1)	R _{0JA}	313	°C/W
Operating and Storage Temperature Range	TJ, T _{STG}	-55 to +150	٥C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 4)								
Drain-Source Breakdown Voltage	BV _{DSS}	-50			V	$V_{GS} = 0V, I_D = -250 \mu A$		
Zero Gate Voltage Drain Current	I _{DSS}			-10	μA	$V_{DS} = -50V, V_{GS} = 0V$		
Gate-Body Leakage	I _{GSS}	_		± 500	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$		
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V _{GS(th)}	-0.7		-1.0	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$		
Static Drain-Source On-Resistance	Page (a)		4.6	6	Ω	$V_{GS} = -4V, I_D = -100mA$		
Static Drain-Source Officesistance	R _{DS (ON)}	_	6.0	8	52	$V_{GS} = -2.5V, I_D = -80mA$		
Forward Transfer Admittance	Y _{fs}	100			mS	$V_{DS} = -5V, I_D = -100mA$		
Diode Forward Voltage	V _{SD}			-1.2	V	$V_{GS} = 0V, I_{S} = -100mA$		
DYNAMIC CHARACTERISTICS								
Input Capacitance	Ciss	_	29		рF			
Output Capacitance	Coss		7.3	_	рF	$V_{DS} = -25V, V_{GS} = 0V, f = 1.0MHz$		
Reverse Transfer Capacitance	Crss		2.5		рF]		

Notes: 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001,

which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

2. No purposefully added lead.

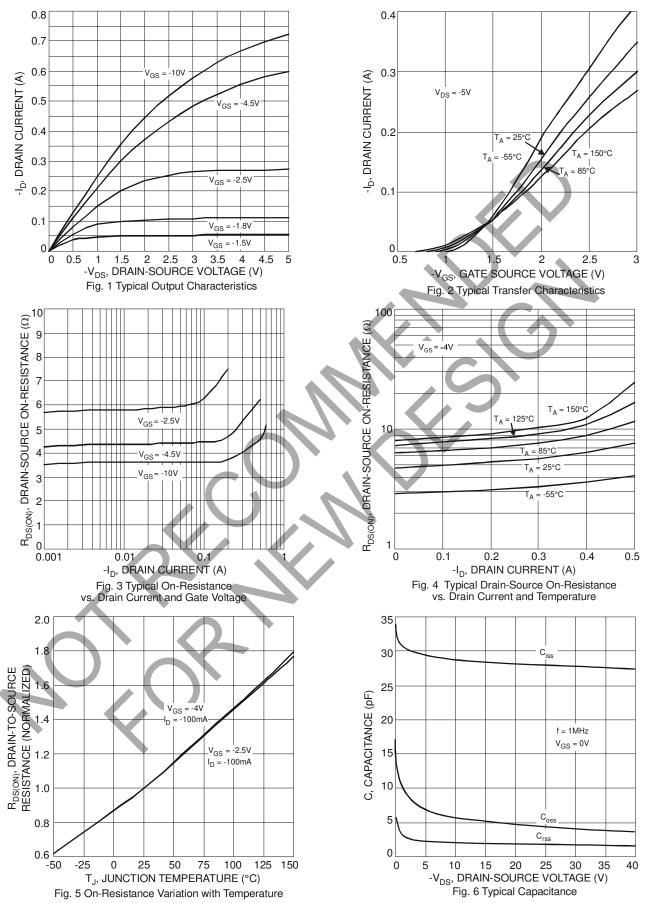
3. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

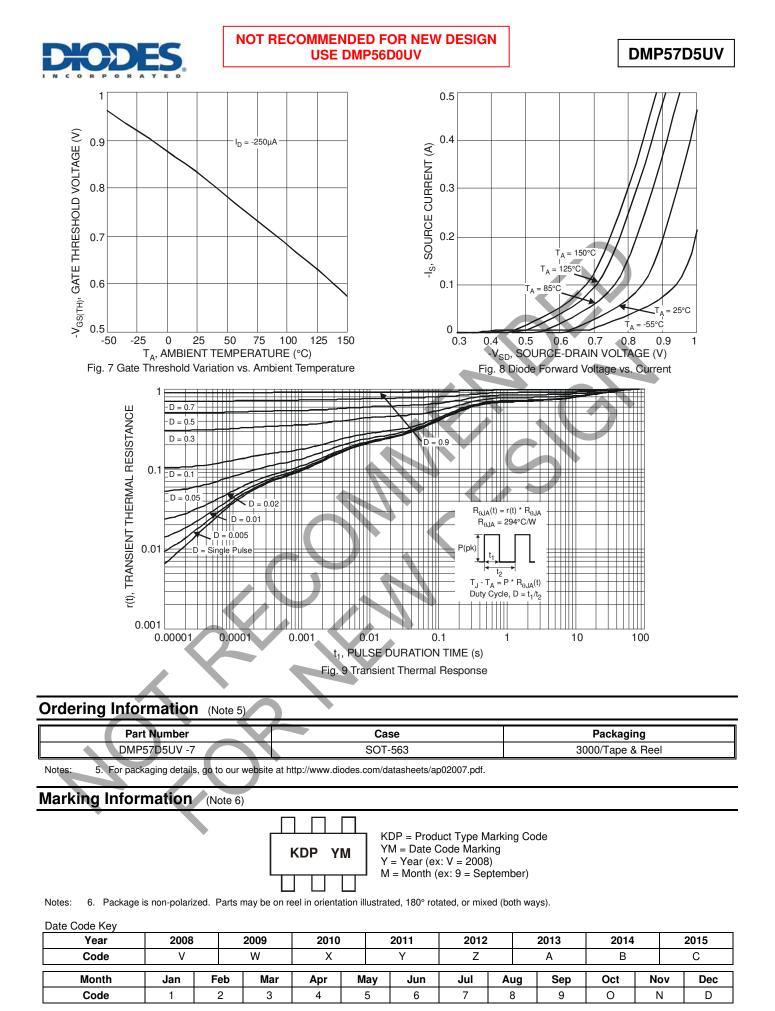
4. Short duration pulse test used to minimize self-heating effect.



NOT RECOMMENDED FOR NEW DESIGN USE DMP56D0UV

DMP57D5UV

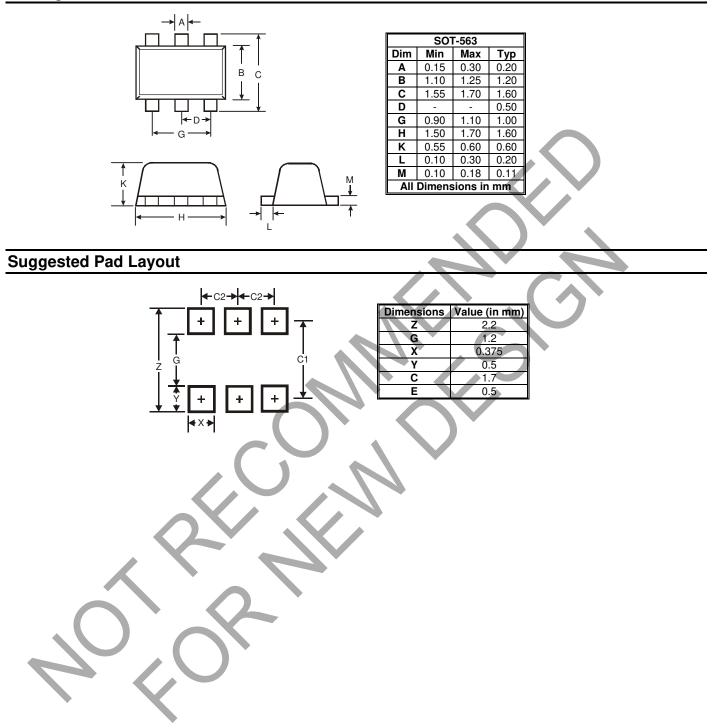




3 of 5 www.diodes.com



Package Outline Dimensions





IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2009, Diodes Incorporated

www.diodes.com